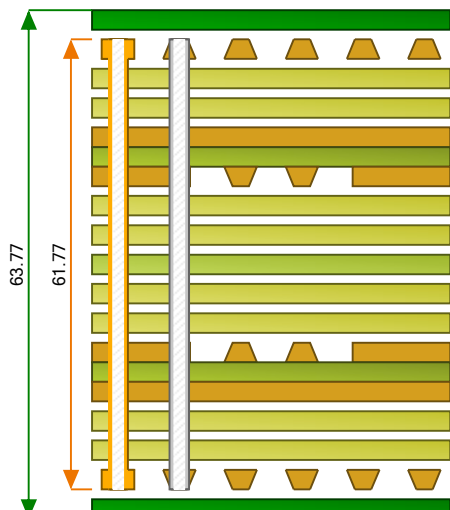



Layer	Stack up	Description	Processed Thickness	Isolation Distance (Summed)	Copper Coverage	εr	Loss Tangent	Impedance ID	
1		Taiyo PSR 4000 HFX DI-GREEN	1.000			3.500	0.0270		
		Copper Foil 12 microns	1.850		100.000			1, 2, 3, 4, 5	
		Iteq IT180A Prepreg 106 RC71-NEW	1.716	3.432		3.790	0.0150		
2		Iteq IT180A Prepreg 106 RC71-NEW	1.716	-		3.790	0.0150		
				1.260		50.000			
		3	Iteq IT180A 3 mil core 1/1	3.000	3.000		3.700	0.0150	
			1.260		40.000		6, 7, 8, 9, 10		
Iteq IT180A Prepreg 7628 RC43-NEW			6.542	40.168		4.450	0.0150		
4		Iteq IT180A Prepreg 7628 RC43-NEW	6.542	-		4.450	0.0150		
		Iteq IT180A 14 mil core H/H	14.000	-		4.540	0.0150		
		Iteq IT180A Prepreg 7628 RC43-NEW	6.542	-		4.450	0.0150		
		Iteq IT180A Prepreg 7628 RC43-NEW	6.542	-		4.450	0.0150		
				1.260		40.000			
		5	Iteq IT180A 3 mil core 1/1	3.000	3.000		3.700	0.0150	
			1.260		50.000				
Iteq IT180A Prepreg 106 RC71-NEW			1.716	3.432		3.790	0.0150		
6		Iteq IT180A Prepreg 106 RC71-NEW	1.716	-		3.790	0.0150		
		Copper Foil 12 microns	1.850		100.000			11, 12, 13, 14, 15	
	Taiyo PSR 4000 HFX DI-GREEN	1.000			3.500	0.0270			


Copper Thickness = 8.740 | Dielectric Thickness = 53.032 | Solder Mask Thickness = 2.000 | Stack Up Thickness = 61.772 | Stack Up Thickness with Soldermask = 63.772

Impedance ID	Impedance Signal Layer	Structure Name	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance	Target Impedance	Tol (+/- %)
1	1	Coated Microstrip 1B	2	0	9.050	0.000	0.000	39.110	40.000	10.000
2	1	Coated Microstrip 1B	2	0	5.800	0.000	0.000	49.520	50.000	10.000
3	1	Edge Coupled Coated Microstrip 1B	2	0	6.020	4.800	0.000	80.120	80.000	10.000
4	1	Edge Coupled Coated Microstrip 1B	2	0	4.200	4.400	0.000	90.570	90.000	10.000
5	1	Edge Coupled Coated Microstrip 1B	2	0	4.250	7.150	0.000	99.900	100.000	10.000
6	3	Offset Stripline 1B1A	2	4	5.800	0.000	0.000	41.400	40.000	10.000
7	3	Offset Stripline 1B1A	2	4	3.600	0.000	0.000	51.300	50.000	10.000
8	3	Edge Coupled Offset Stripline 1B1A	2	4	3.700	6.000	0.000	87.950	90.000	10.000
9	3	Edge Coupled Offset Stripline 1B1A	2	4	3.200	7.500	0.000	96.390	100.000	10.000

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Author: -							
Department: Engg-CAM							
Site: www.hiqelectronics.com							

Impedance ID	Impedance Signal Layer	Structure Name	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width (W1)	Trace Separation (S1)	Ground Strip Separation (D1)	Calculated Impedance	Target Impedance	Tol (+/- %)	
10	3	Edge Coupled Offset Stripline 1B1A	2	4	4.200	4.300	0.000	78.500	80.000	10.000	
11	6	Coated Microstrip 1B	5	0	9.050	0.000	0.000	39.110	40.000	10.000	
12	6	Coated Microstrip 1B	5	0	5.800	0.000	0.000	49.520	50.000	10.000	
13	6	Edge Coupled Coated Microstrip 1B	5	0	6.020	4.800	0.000	80.120	80.000	10.000	
14	6	Edge Coupled Coated Microstrip 1B	5	0	4.200	4.400	0.000	90.570	90.000	10.000	
15	6	Edge Coupled Coated Microstrip 1B	5	0	4.250	7.150	0.000	99.900	100.000	10.000	

Notes

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